

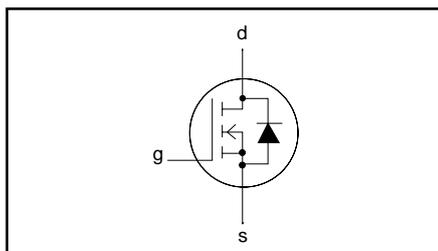
# N-channel TrenchMOS™ transistor Logic level FET

PHN1018

## FEATURES

- 'Trench' technology
- Low on-state resistance
- Fast switching
- Low-profile surface mount package
- Logic level compatible

## SYMBOL



## QUICK REFERENCE DATA

|  |
|--|
| $V_{DSS} = 25\text{ V}$  |
| $I_D = 9.6\text{ A}$   |
| $R_{DS(ON)} \leq 18\text{ m}\Omega$ ( $V_{GS} = 10\text{ V}$ ) |
| $R_{DS(ON)} \leq 21\text{ m}\Omega$ ( $V_{GS} = 5\text{ V}$ )  |

## GENERAL DESCRIPTION

N-channel enhancement mode logic level field-effect power transistor in a surface mounting plastic package using 'trench' technology.

### Application:-

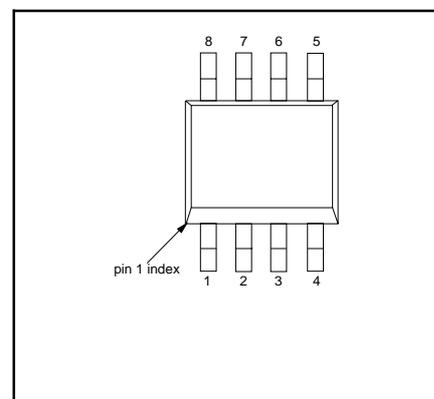
- High frequency computer motherboard d.c. to d.c. converters

The PHN1018 is supplied in the SOT96-1 (SO8) surface mounting package.

## PINNING

| PIN | DESCRIPTION |
|-----|-------------|
| 1-3 | source      |
| 4   | gate        |
| 5-8 | drain       |

## SOT96-1 (SO8)



## LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134)

| SYMBOL         | PARAMETER                                  | CONDITIONS  | MIN. | MAX.       | UNIT             |
|----------------|--|---|------|------------|------------------|
| $V_{DSS}$      | Drain-source voltage                       | $T_j = 25\text{ }^\circ\text{C}$ to $150\text{ }^\circ\text{C}$                                   | -    | 25         | V                |
| $V_{DGR}$      | Drain-gate voltage                         | $T_j = 25\text{ }^\circ\text{C}$ to $150\text{ }^\circ\text{C}$ ;<br>$R_{GS} = 20\text{ k}\Omega$ | -    | 25         | V                |
| $V_{GS}$       | Gate-source voltage (DC)                   | -   | -    | $\pm 15$   | V                |
| $V_{GSM}$      | Gate-source voltage (pulse peak value)     | -   | -    | $\pm 20$   | V                |
| $I_D$          | Drain current ( $t_p \leq 10\text{ s}$ )   | $T_a = 25\text{ }^\circ\text{C}$<br>$T_a = 70\text{ }^\circ\text{C}$                              | -    | 9.6<br>7.7 | A<br>A           |
| $I_{DM}$       | Drain current (pulse peak value)           | $T_a = 25\text{ }^\circ\text{C}$  | -    | 38         | A                |
| $P_{tot}$      | Total power dissipation                    | $T_a = 25\text{ }^\circ\text{C}$<br>$T_a = 70\text{ }^\circ\text{C}$                              | -    | 2.5<br>1.6 | W<br>W           |
| $T_j, T_{stg}$ | Operating junction and storage temperature | -   | - 55 | 150        | $^\circ\text{C}$ |

## THERMAL RESISTANCES

| SYMBOL        | PARAMETER                              | CONDITIONS   | TYP. | MAX. | UNIT |
|---------------|--|--|------|------|------|
| $R_{th\ j-a}$ | Thermal resistance junction to ambient | Surface mounted, FR4 board, $t \leq 10\text{ sec}$ | -    | 50   | K/W  |
| $R_{th\ j-a}$ | Thermal resistance junction to ambient | Surface mounted, FR4 board                         | 150  | -    | K/W  |

# N-channel TrenchMOS™ transistor

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### ELECTRICAL CHARACTERISTICS

T<sub>j</sub> = 25 °C unless otherwise specified

| SYMBOL               | PARAMETER                        | CONDITIONS   | MIN.          | TYP.          | MAX.           | UNIT           |
|----------------------|----------------------------------|--|---------------|---------------|----------------|----------------|
| V <sub>(BR)DSS</sub> | Drain-source breakdown voltage   | V <sub>GS</sub> = 0 V; I <sub>D</sub> = 0.25 mA;<br>T <sub>j</sub> = -55 °C  | 25<br>22      | -<br>-        | -<br>-         | V<br>V         |
| V <sub>GS(TO)</sub>  | Gate threshold voltage           | V <sub>DS</sub> = V <sub>GS</sub> ; I <sub>D</sub> = 1 mA<br>T <sub>j</sub> = 150 °C<br>T <sub>j</sub> = -55 °C  | 1<br>0.6<br>- | 1.5<br>-<br>- | 2<br>-<br>2.3  | V<br>V<br>V    |
| R <sub>DS(ON)</sub>  | Drain-source on-state resistance | V <sub>GS</sub> = 10 V; I <sub>D</sub> = 10 A<br>V <sub>GS</sub> = 5 V; I <sub>D</sub> = 10 A<br>V <sub>GS</sub> = 5 V; I <sub>D</sub> = 10 A; T <sub>j</sub> = 150 °C | -<br>-<br>-   | 13<br>18<br>- | 18<br>21<br>36 | mΩ<br>mΩ<br>mΩ |
| g <sub>fs</sub>      | Forward transconductance         | V <sub>DS</sub> = 25 V; I <sub>D</sub> = 10 A  | 8             | 25            | -              | S              |
| I <sub>GSS</sub>     | Gate source leakage current      | V <sub>GS</sub> = ±5 V; V <sub>DS</sub> = 0 V  | -             | 10            | 100            | nA             |
| I <sub>DSS</sub>     | Zero gate voltage drain current  | V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0 V;<br>T <sub>j</sub> = 150 °C  | -             | 0.05          | 10<br>500      | μA<br>μA       |
| Q <sub>g(tot)</sub>  | Total gate charge                | I <sub>D</sub> = 10 A; V <sub>DD</sub> = 15 V; V <sub>GS</sub> = 5 V   | -             | 17            | -              | nC             |
| Q <sub>gs</sub>      | Gate-source charge               |  | -             | 4             | -              | nC             |
| Q <sub>gd</sub>      | Gate-drain (Miller) charge       |  | -             | 6             | -              | nC             |
| t <sub>d on</sub>    | Turn-on delay time               | V <sub>DD</sub> = 15 V; I <sub>D</sub> = 25 A;   | -             | 6.4           | 12             | ns             |
| t <sub>r</sub>       | Turn-on rise time                | V <sub>GS</sub> = 10 V; R <sub>G</sub> = 5 Ω   | -             | 62            | 75             | ns             |
| t <sub>d off</sub>   | Turn-off delay time              | Resistive load   | -             | 50            | 75             | ns             |
| t <sub>f</sub>       | Turn-off fall time               |  | -             | 30            | 45             | ns             |
| L <sub>d</sub>       | Internal drain inductance        | Drain leads to centre of die   | -             | 1             | -              | nH             |
| L <sub>s</sub>       | Internal source inductance       | Source leads to source bond pad  | -             | 3             | -              | nH             |
| C <sub>ISS</sub>     | Input capacitance                | V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 20 V; f = 1 MHz   | -             | 1050          | -              | pF             |
| C <sub>OSS</sub>     | Output capacitance               |  | -             | 330           | -              | pF             |
| C <sub>rSS</sub>     | Feedback capacitance             |  | -             | 220           | -              | pF             |

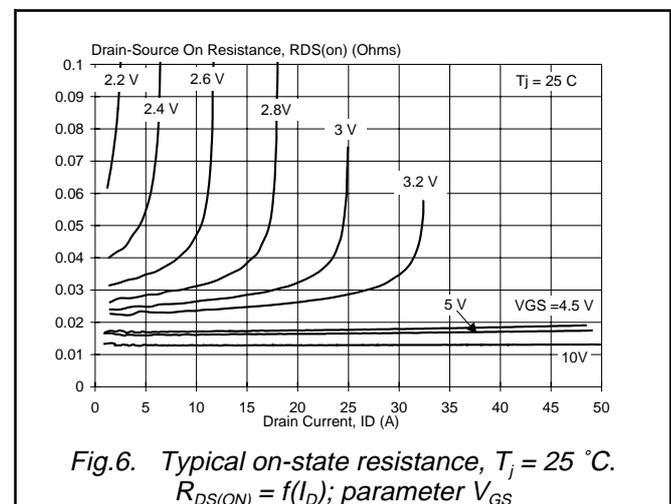
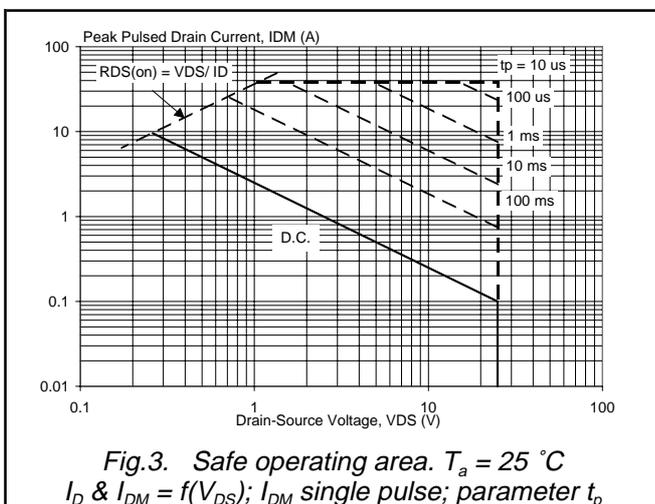
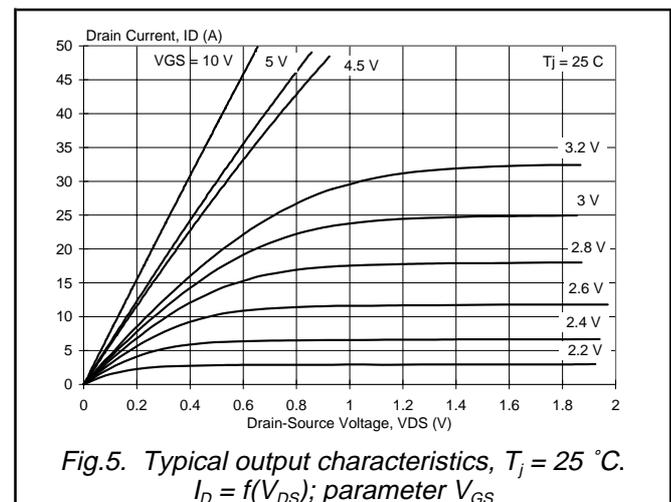
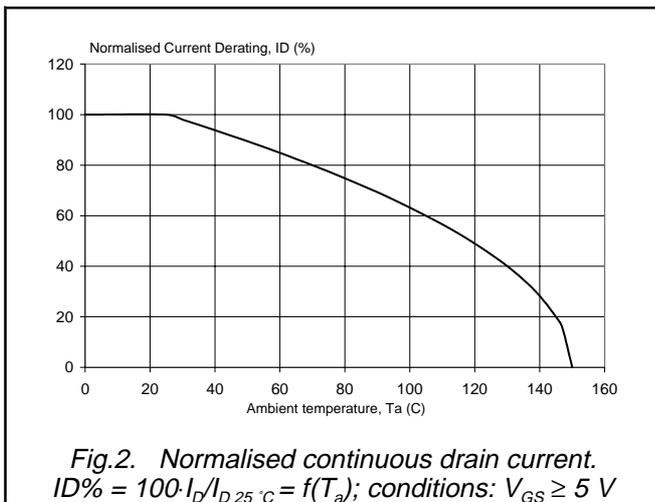
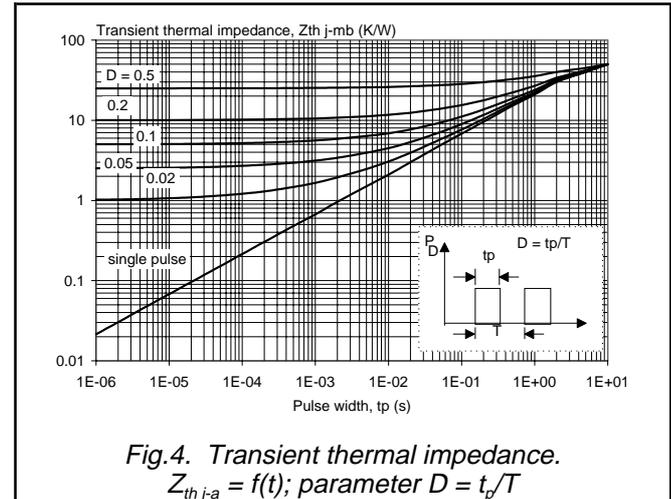
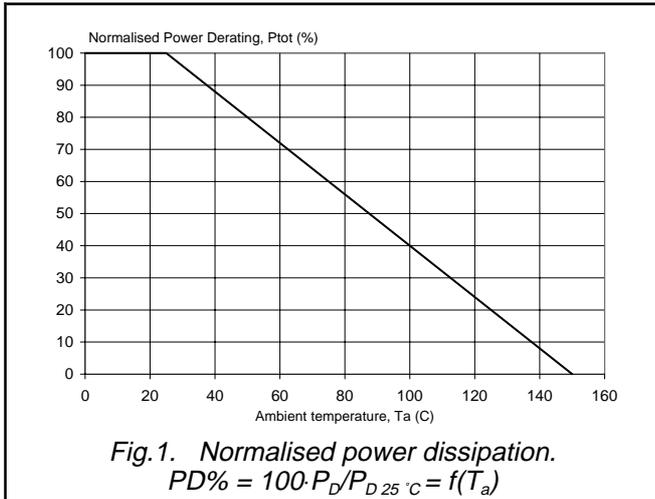
### REVERSE DIODE LIMITING VALUES AND CHARACTERISTICS

T<sub>j</sub> = 25 °C unless otherwise specified

| SYMBOL           | PARAMETER                              | CONDITIONS  | MIN. | TYP. | MAX. | UNIT |
|------------------|--|---|------|------|------|------|
| I <sub>DR</sub>  | Continuous source current (body diode) | T <sub>a</sub> = 25 °C, t <sub>p</sub> ≤ 10 s           | -    | -    | 9.6  | A    |
| I <sub>DRM</sub> | Pulsed source current (body diode)     |   | -    | -    | 38   | A    |
| V <sub>SD</sub>  | Diode forward voltage                  | I <sub>F</sub> = 10 A; V <sub>GS</sub> = 0 V            | -    | 0.83 | 1.2  | V    |
| t <sub>rr</sub>  | Reverse recovery time                  | I <sub>F</sub> = 10 A; -di <sub>F</sub> /dt = 100 A/μs; | -    | 100  | -    | ns   |
| Q <sub>rr</sub>  | Reverse recovery charge                | V <sub>GS</sub> = 0 V; V <sub>R</sub> = 25 V            | -    | 0.13 | -    | μC   |

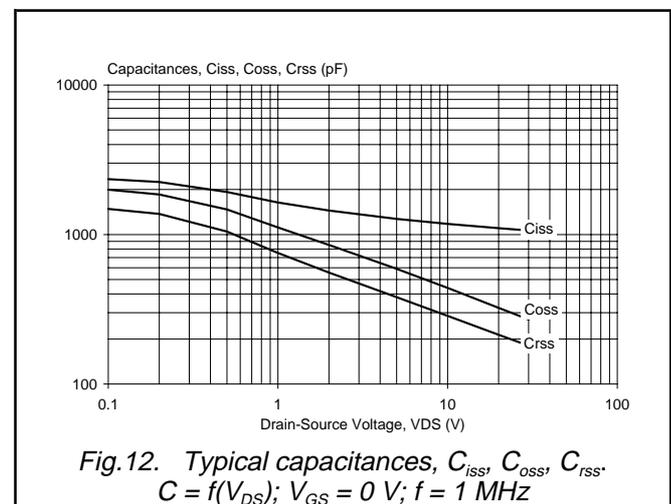
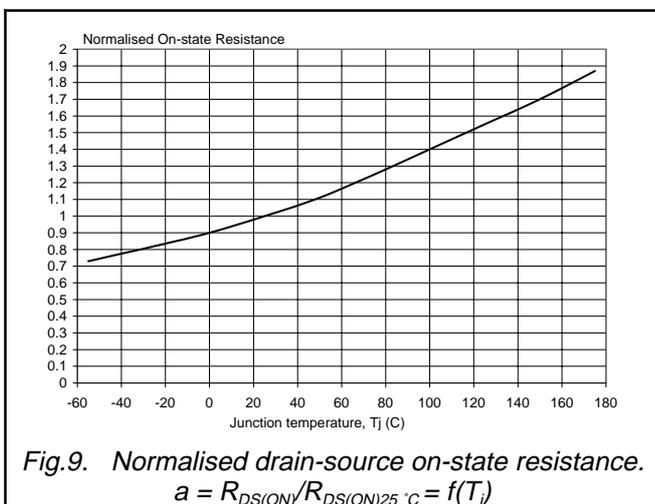
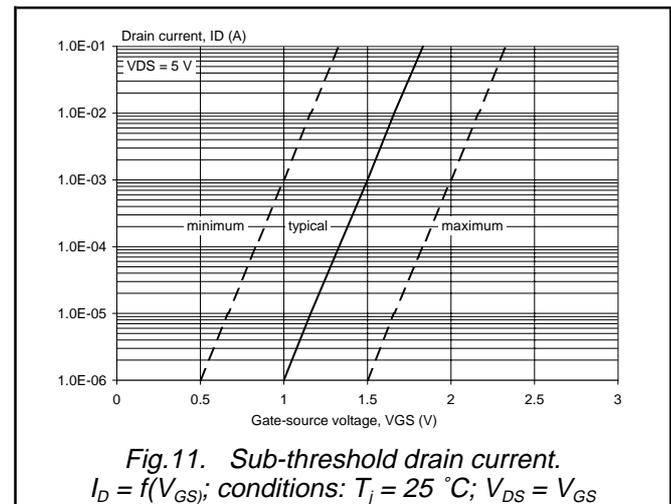
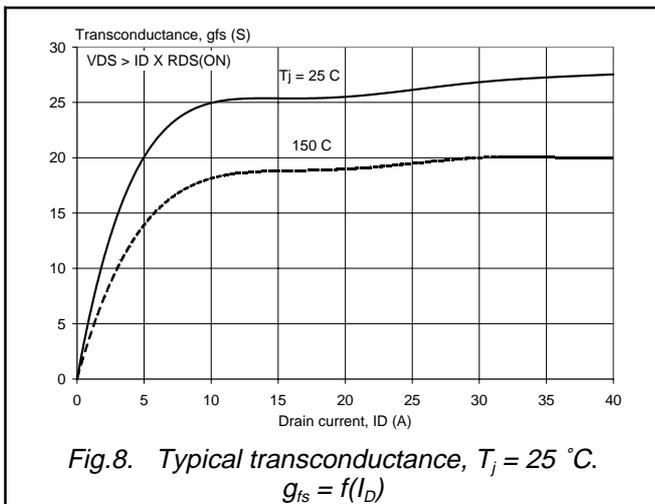
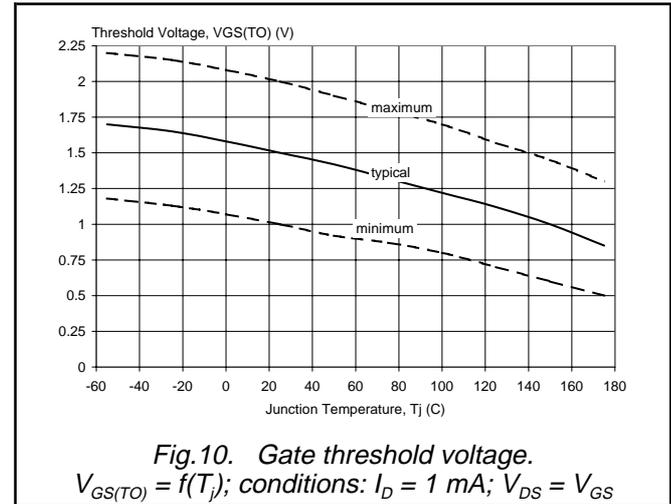
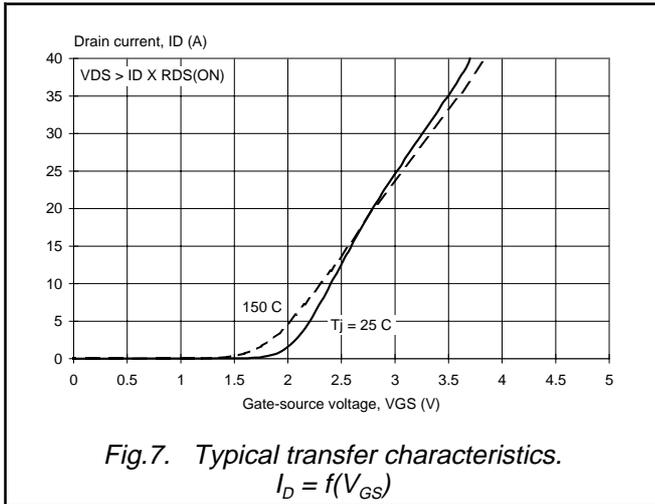
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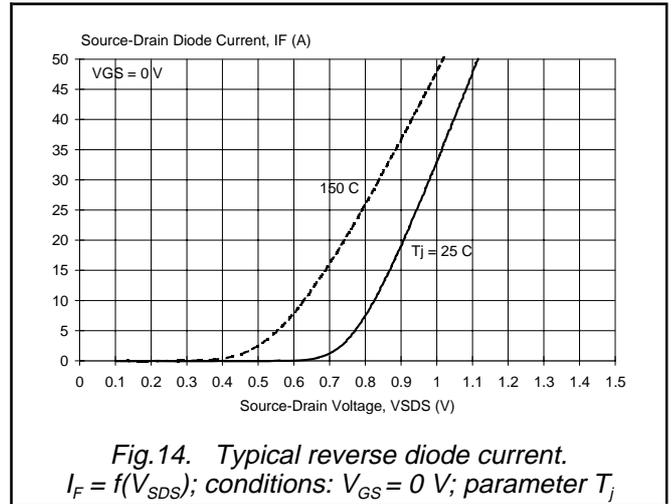
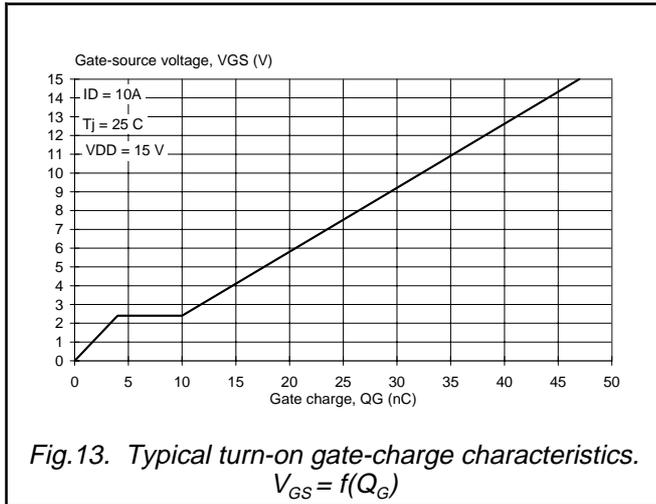
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Logic level FET

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N-channel TrenchMOS™ transistor  
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MECHANICAL DATA

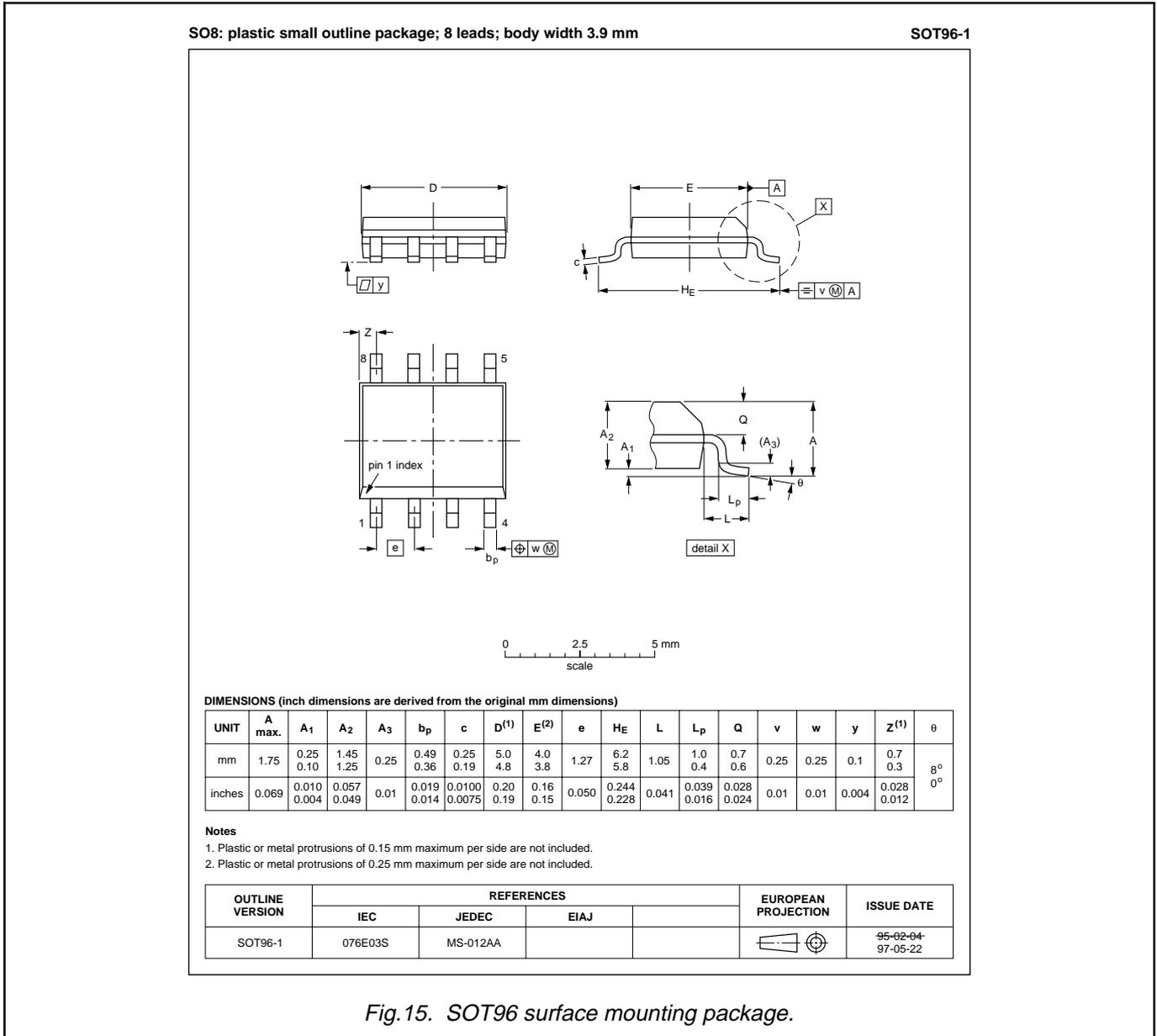


Fig. 15. SOT96 surface mounting package.

Notes

1. This product is supplied in anti-static packaging. The gate-source input must be protected against static discharge during transport or handling.
2. Refer to Integrated Circuit Packages, Data Handbook IC26.
3. Epoxy meets UL94 V0 at 1/8".

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### DEFINITIONS

|  |   |
|--|---|
| <b>Data sheet status</b>   |   |
| Objective specification  | This data sheet contains target or goal specifications for product development.       |
| Preliminary specification  | This data sheet contains preliminary data; supplementary data may be published later. |
| Product specification  | This data sheet contains final product specifications.                                |
| <b>Limiting values</b>   |   |
| Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability. |   |
| <b>Application information</b>   |   |
| Where application information is given, it is advisory and does not form part of the specification.  |   |
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